

CIRCUIT BOARD TRANSFERRING APPARATUS AND METHOD AND SOLDER BALL MOUNTING METHOD

Abstract

By photographing pad forming faces of CSPs 400 to recognize a pad arrangement through image processing so as to transfer and position the CSPs 400 in accordance with the recognition result of the pad arrangement, even if pads 401 are formed in any arrangement state in the CSPs 400 to be transferred, the positional relation between the pads 401 included in the CSPs 400 is made to always accurately coincide with the positional region between a plurality of solder ball attracting nozzles of a solder ball mounting apparatus.